

Bill of Materials

TI DESIGNS

TIDM-LPSM

Item	Qty	Reference/Designator	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	Altium Footprint
1	1	C1	10uF	CAP, CERM, 10uF, 6.3V, +/-10%, X5R, 0805	Murata	GRM219R60J106KE19D		C0805C106K9PAC
2	1	C2	0.1uF	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	Murata	GRM188R71C104KA01D		0603YC104JAT2A
3	2	J1, J6		Header, 100mil, 3x1, Tin, TH	Würth Electronics	61300311121		5-146278-3
4	1	J2		Terminal Block, 2x1, 5.08mm, TH	On Shore Technology	OSTTC022162		282841-2
5	2	J3		Header, 100mil, 10x1, Tin, TH	Samtec	SSW-110-23-F-S		Custom
6	1	J4		Header, 100mil, 2x1, Tin, TH	Würth Electronics	61300211121		5-146278-2
7	1	J5		Terminal Block, 4x1, 5.08mm, TH	On Shore Technology	OSTTA044163		39544-3004
8	1	R1	20k	RES, 20k ohm, 5%, 0.1W, 0603	Panasonic	ERJ-3EKF2002V		CRCW060320K0JNEA
9	2	R2, R3	0.01	RES, 0.01 ohm, 1%, 3W, 2512	TT Electronics	LRMAP2512-R01FT4		CRA2512-FZ-R010ELF
10	1	R4	DNP					CRCW040210K0JNED
11	2	R5, R6	10k	RES, 10k ohm, 5%, 0.063W, 0402	Panasonic	ERJ-3GEYJ103V		CRCW040210K0JNED
12	1	U1	DRV8836	IC, DUAL LOW VOLTAGE H-BRIDGE	Texas Instruments	DRV8836DSSR		DRV8835DSSR
13	1	U2	INA199A1	Current-Shunt Monitor	Texas Instruments	INA199A1DCKR		INA199A1DCK

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